



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/734,195  
Applicant : Kwun-Yao Ho et al.  
Filed : December 15, 2003  
Title : HIGH-DENSITY MULTICHIP MODULE  
PACKAGE  
TC/A.U. : 2813  
Examiner : BRYANT, DELORIS S  
Docket No. : 025796-00014

**RESPONSE UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

October 6, 2006

Sir:

In reply to the Official Action dated June 29, 2006, the period for response being extended from September 29, 2006 to October 29, 2006, by the attached Petition for Extension of Time, please amend the above-identified application as set forth below:

**Amendments** to the Claims begin on page 2 of this paper.

**Remarks** begin on page 5 of this paper.